



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC0902NS		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001648292					
<b>Package</b>				PG-TDSON-8-6		<b>Weight*</b>		118.18 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.419	0.35	0.35	3543	3543	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96		
	non noble metal	iron	7439-89-6	0.038	0.03		320		
	non noble metal	copper	7440-50-8	37.762	31.96	32.00	319526	319942	
	noble metal	gold	7440-57-5	0.046	0.04	0.04	386	386	
wire	organic material	carbon black	1333-86-4	0.088	0.07		745		
encapsulation	plastics	epoxy resin	-	6.248	5.29		52865		
	inorganic material	silicondioxide	60676-86-0	37.661	31.87	37.23	318678	372288	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12283	12283	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1401	1401	
solder	non noble metal	tin	7440-31-5	0.013	0.01		108		
	noble metal	silver	7440-22-4	0.016	0.01		134		
	non noble metal	lead	7439-92-1	0.607	0.51	0.53	5135	5377	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29		
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96		
	non noble metal	copper	7440-50-8	11.320	9.58	9.59	95786	95911	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57		
	non noble metal	iron	7439-89-6	0.022	0.02		189		
	non noble metal	copper	7440-50-8	22.292	18.86	18.89	188623	188869	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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